

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

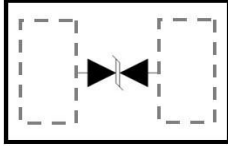


PLED

Product data sheet

Features

PIN CONFIGURATION



DFN1006

- Ultra-low Capacitance 0.5pF
- Low Clamping Voltage
- Small Body Outline Dimensions: 0.039" x 0.024" (1.0 mm x 0.60 mm)
- Low Body Height: 0.019" (0.5 mm)
- Stand-off Voltage: 5.0V
- Low Leakage
- Response Time is Typically < 1 ns
- IEC61000-4-2 Level 4 ESD Protection for data lines
- These are Pb-Free Devices

Applications

- 10/100/1000 Mbits/s Ethernet
- FireWire
- Display ports
- MDDI ports
- Digital Visual Interface (DVI)
- Cellular handsets & accessories
- Computer and peripherals

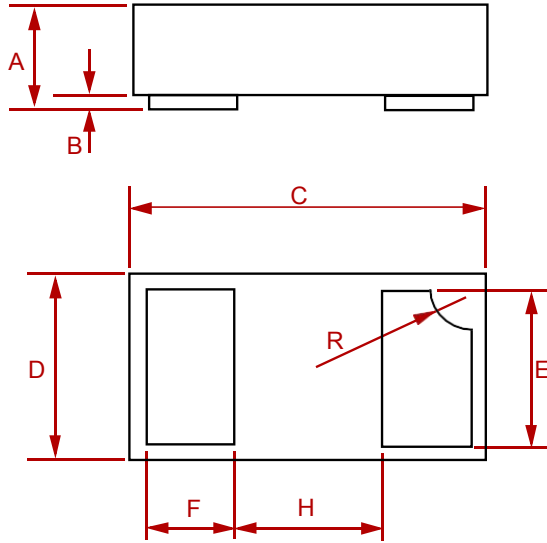
Electrical Characteristics @ Ta=25°C unless otherwise

P/N	VRWM @IR		VBR@ImA	VC@1A	VC@IPP		CJ
	V	μA	V	V	V	A	pF
		MAX	MIN	MAX	MAX		MAX
RCLAMP0531T-MS	5	0.5	6.3	11	16	3	0.5

Maximum Rating @ Ta=25°C unless otherwise specified

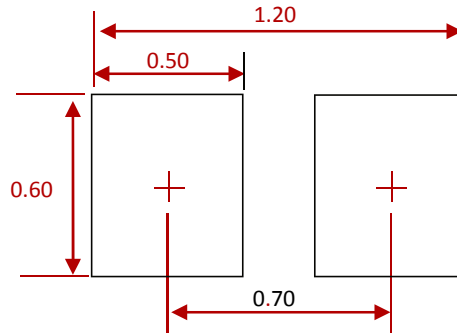
Symbol	Parameter	Ratings	Units
ESD	IEC 61000-4-2 (HBM-ESD)	Contact	8
		Air	15
TL	Lead Soldering Temperature	260(10sec.)	°C
TJ	Operating Temperature	-55 to +125	°C
TSTG	Storage Temperature	-55 to +150	°C

PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

Suggested Pad Layout



NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
RCLAMP0531T-MS	DFN1006	10000

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